PCN Number:	20190304002.0 PCN Date: March 06, 2019			2019		
Title: Datasheet for	·					
Customer Contact:	PCN Manager		Dept:	Quality Services		
Change Type:						
Assembly Site		Design		Wafe	er Bump Site	
Assembly Process					Wafer Bump Material	
Assembly Materials		Part numb	Part number change		Wafer Bump Process	
Mechanical Specification		Test Site			Wafer Fab Site	
Packing/Shipping/Labeling		Test Proce	Test Process		er Fab Materials	
					er Fab Process	
Notification Details						
Description of Change:						
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. TEXAS TPS65094						
INSTRUMENTS SWCS133C - SEPTEMBER 2015 - REVISED FEBRUARY 2019						
Changes from Revision B (F	ebruary 2017) to	Revision C			Page	
Changed the description of the VTTFB pin in the Pin Functions table						
			Chanas		Change To	
Device Family			Change I		Change To:	
TPS65094			SWCS13		SWCS133C	
These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/TPS65094						
Reason for Change:						
To accurately reflect device characteristics.						
,						
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to						
the actual device.						
Changes to product identification resulting from this PCN: None.						
Product Affected:	TDCCTCC	40405016	TDCCECCAA	ADDCIAD T	TDCCE0044 A0DCC	
TPS650940A0RSKR		40A0RSKT	TPS650941A		TPS650941A0RSKT	
TPS650942A0RSKR	TPS65094	42A0RSKT	TPS650944A	AORSKR	TPS650944A0RSKT	

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com